



DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	Rds(on)	I _D T _A = 25°C
30V	4.2Ω @ V _{GS} = 4.5V	200mA
300	2.8Ω @ V _{GS} = 10V	260mA

Description

This new generation MOSFET has been designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- DC-DC Converters
- Power management functions
- Battery Operated Systems and Solid-State Relays
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories, Transistors, etc

Features

- Dual N-Channel MOSFET
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Small Surface Mount Package
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

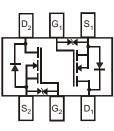
Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 (3)
- Terminal Connections: See Diagram
- Weight: 0.006 grams (approximate)

ESD PROTECTED



Top View



Top View Internal Schematic

Ordering Information (Note 4)

Part Number	Case	Packaging
DMN63D8LDW-7	SOT363	3000/Tape & Reel
DMN63D8LDW-13	SOT363	10000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com.

Marking Information

Ν	/M	4	Y	N
V	Y	t	'WI	Ν

MM4 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: Z = 2012) M = Month (ex: 9 = September)

Date	Code	Key
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Year	201 ⁻	1	2012		2013	20	14	2015		2016	2	2017
Code	Y		Z		А	E	3	С		D		E
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

	Characteristic			Symbol	Value	Units
Drain-Source Voltage				V _{DSS}	30	V
Gate-Source Voltage				V _{GSS}	±20	V
Continuous Drain Current (Note 5)	$V_{GS} = 10V$	Steady State	T _A = +25°C T _A = +70°C	ID	220 170	mA
Continuous Drain Current (Note 6)	$V_{GS} = 10V$	Steady State	T _A = +25°C T _A = +70°C	ID	260 210	mA
Pulsed Drain Current (10µs pulse, dut	ty cycle = 1%)			I _{DM}	800	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Total Power Dissipation	(Note 5)	P	300	mW	
	(Note 6)	PD	400		
Thermal Desistance Junction to Ambient	(Note 5)	6	435		
Thermal Resistance, Junction to Ambient	(Note 6)	$R_{ ext{ heta}JA}$	330	°C/W	
Thermal Resistance, Junction to Case (Note		$R_{\theta JC}$	139		
Operating and Storage Temperature Range	·	T _{J,} T _{STG}	-55 to 150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

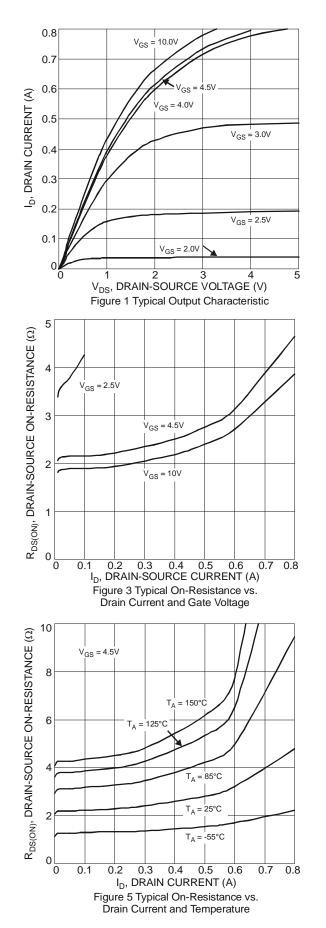
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)				_		
Drain-Source Breakdown Voltage	BV _{DSS}	30		_	V	$V_{GS} = 0V, I_D = 250 \mu A$
Zero Gate Voltage Drain Current	IDSS	_	_	1.0	μA	$V_{DS} = 30V, V_{GS} = 0V$
Gate-Body Leakage	I _{GSS}	_		±10.0	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(th)}	0.8		1.5	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
				2.8		$V_{GS} = 10.0V, I_D = 250mA$
		_		3.8		$V_{GS} = 5V, I_D = 250mA$
Static Drain-Source On-Resistance	R _{DS (ON)}	_	_	4.2	Ω	$V_{GS} = 4.5V, I_D = 250mA$
	. ,	_		4.5		$V_{GS} = 4.0V, I_D = 250mA$
		_		13		$V_{GS} = 2.5V, I_D = 10mA$
Forward Transconductance	g fs	80			mS	V _{DS} = 10V, I _D = 0.115A
Diode Forward Voltage	Vsd	-	0.8	1.2	V	$V_{GS} = 0V, I_{S} = 115mA$
DYNAMIC CHARACTERISTICS (Note 8)						·
Input Capacitance	Ciss	_	22.0			
Output Capacitance	Coss	_	3.2	_	pF	$V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$
Reverse Transfer Capacitance	Crss	_	2.0	_		
Gate Resistance	R _G	_	79.9	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge V _{GS} = 10V	Qq	_	0.87	_		
Total Gate Charge V _{GS} = 4.5V	Qq		0.43		nC	$V_{GS} = 10V, V_{DS} = 30V,$
Gate-Source Charge	Q _{gs}	_	0.11	_	nc	I _D = 150mA
Gate-Drain Charge	Q _{gd}	_	0.11			
Turn-On Delay Time	t _{D(on)}	_	3.3			
Turn-On Rise Time	tr	_	3.2		nS	$V_{DD} = 30V, I_D = 0.115A, V_{GEN} = 10V$
Turn-Off Delay Time	t _{D(off)}	_	12.0		ns	$R_{GEN} = 25\Omega$
Turn-Off Fall Time	t _f		6.3	_		

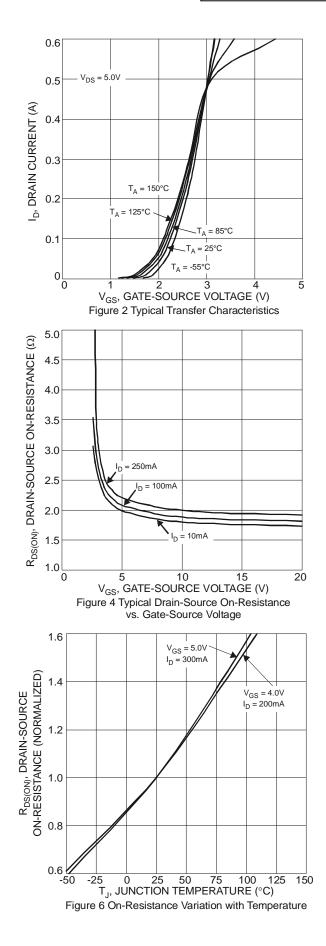
 Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad layout
Short duration pulse test used to minimize self-heating effect. Notes:

8. Guaranteed by design. Not subject to production testing.

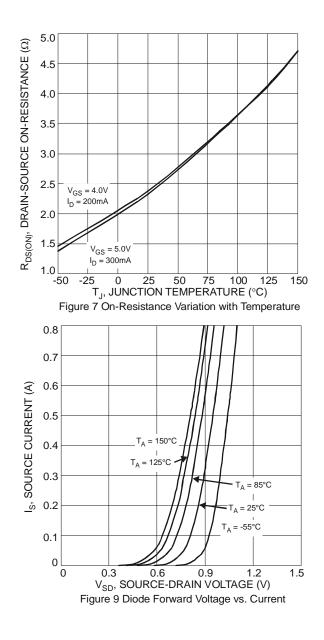
DMN63D8LDW











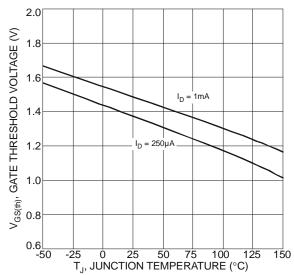
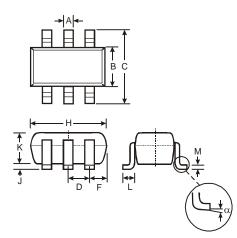


Figure 8 Gate Threshold Variation vs. Ambient Temperature



Package Outline Dimensions

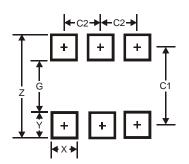
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	SC	DT363	
Dim	Min	Max	Тур
Α	0.10	0.30	0.25
В	1.15	1.35	1.30
С	2.00	2.20	2.10
D		0.65 Ty	p
F	0.40	0.45	0.425
Н	1.80	2.20	2.15
J	0	0.10	0.05
Κ	0.90	1.00	1.00
L	0.25	0.40	0.30
М	0.10	0.22	0.11
α	0°	8°	-
All	Dimen	isions i	n mm

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Y	0.6
C1	1.9
C2	0.65



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